

INTEGRATED CIRCUITS

DATA SHEET

74AHC123A; 74AHCT123A Dual retriggerable monostable multivibrator with reset

Product specification
File under Integrated Circuits, IC06

2000 Mar 15

Dual retriggerable monostable multivibrator with reset

**74AHC123A;
74AHCT123A**

FEATURES

- ESD protection:
HBM EIA/JESD22-A114-A exceeds 2000 V
MM EIA/JESD22-A115-A exceeds 200 V
CDM EIA/JESD22-C101 exceeds 1000 V
- All inputs have Schmitt-trigger actions
- Inputs accept voltages higher than V_{CC}
- For AHC only: operates with CMOS input levels
- For AHCT only: operates with TTL input levels
- Specified from -40 to $+85$ °C and -40 to $+125$ °C
- DC triggered from active HIGH or active LOW inputs
- Retriggerable for very long pulses up to 100% duty factor
- Direct reset terminates output pulse
- Output capability: standard (except for nR_{EXT}/C_{EXT}).

DESCRIPTION

The 74AHC/AHCT123A are high-speed Si-gate CMOS devices and are pin compatible with Low power Schottky TTL (LSTTL). They are specified in compliance with JEDEC standard no.7A.

The 74AHC/AHCT123A are dual retriggerable monostable multivibrators with output pulse width control by three methods. The basic pulse time is programmed by selection of an external resistor (R_{EXT}) and capacitor (C_{EXT}). The external resistor and capacitor are normally connected as shown in Fig.6.

Once triggered, the basic output pulse width may be extended by retriggering the gated active LOW-going edge input ($n\bar{A}$) or the active HIGH-going edge input (nB). By repeating this process, the output pulse period ($nQ = \text{HIGH}$, $n\bar{Q} = \text{LOW}$) can be made as long as desired. Alternatively an output delay can be terminated at any time by a LOW-going edge on input nR_D , which also inhibits the triggering.

An internal connection from $n\bar{R}_D$ to the input gate makes it possible to trigger the circuit by a positive-going signal at input nR_D as shown in the function table. Figs 8 and 9 illustrate pulse control by retriggering and early reset. The basic output pulse width is essentially determined by the value of the external timing components R_{EXT} and C_{EXT} . When $C_{EXT} \geq 10$ nF, the typical output pulse width is defined as: $t_W = R_{EXT} \times C_{EXT}$ where t_W = pulse width in ns; R_{EXT} = external resistor in k Ω ; C_{EXT} = external capacitor in pF. Schmitt-trigger action at all inputs makes the circuit highly tolerant to slower input rise and fall times. The '123' is identical to the '423' but can be triggered via the reset input.

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QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25\text{ }^{\circ}\text{C}$; $t_r = t_f \leq 3.0\text{ ns}$.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL		UNIT
			AHC	AHCT	
t_{PHL}/t_{PLH}	propagation delay $n\bar{A}$, nB to nQ , $n\bar{Q}$	$C_L = 15\text{ pF}$; $V_{CC} = 5\text{ V}$; $R_{EXT} = 5\text{ k}\Omega$; $C_{EXT} = 0\text{ pF}$	5.1	5.0	ns
	$n\bar{R}_D$ to nQ , $n\bar{Q}$		5.6	5.2	ns
C_I	input capacitance	$V_I = V_{CC}$ or GND	5	3	pF
C_O	output capacitance		4	4	pF
C_{PD}	power dissipation capacitance	$C_L = 50\text{ pF}$; $f = 1\text{ MHz}$; notes 1 and 2	57	58	pF

Notes

- C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o) \times C_{EXT} \times V_{CC}^2 \times f_o + D \times 16 \times V_{CC}$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

$\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs;

D = duty factor in %;

C_L = output load capacitance in pF;

C_{EXT} = timing capacitance in pF;

V_{CC} = supply voltage in Volts.

- The condition is $V_I = \text{GND to } V_{CC}$.

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FUNCTION TABLE

See note 1.

INPUTS			OUTPUTS	
$n\overline{R}_D$	$n\overline{A}$	nB	nQ	$n\overline{Q}$
L	X	X	L	H
X	H	X	L ⁽²⁾	H ⁽²⁾
X	X	L	L ⁽²⁾	H ⁽²⁾
H	L	↑	 ⁽³⁾	 ⁽⁴⁾
H	↓	H	 ⁽³⁾	 ⁽⁴⁾
↑	L	H	 ⁽³⁾	 ⁽⁴⁾

Notes

- 1 H = HIGH voltage level;
L = LOW voltage level;
X = don't care;
↑ = LOW-to-HIGH CP transition;
↓ = HIGH-to-LOW CP transition.
- 2 If the monostable multivibrator was triggered before this condition was established, the pulse will be continued as programmed.
- 3 One HIGH-level output pulse.
- 4 One LOW-level output pulse.

ORDERING INFORMATION

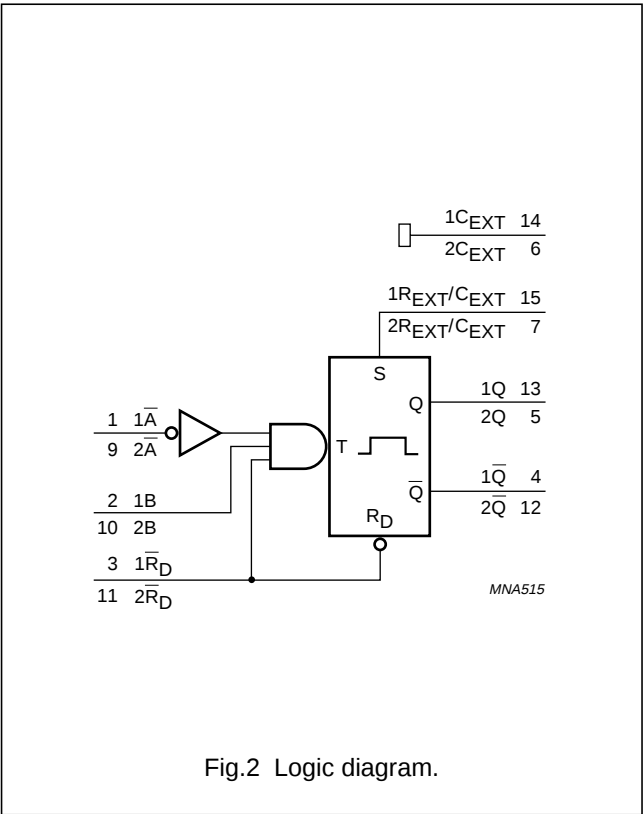
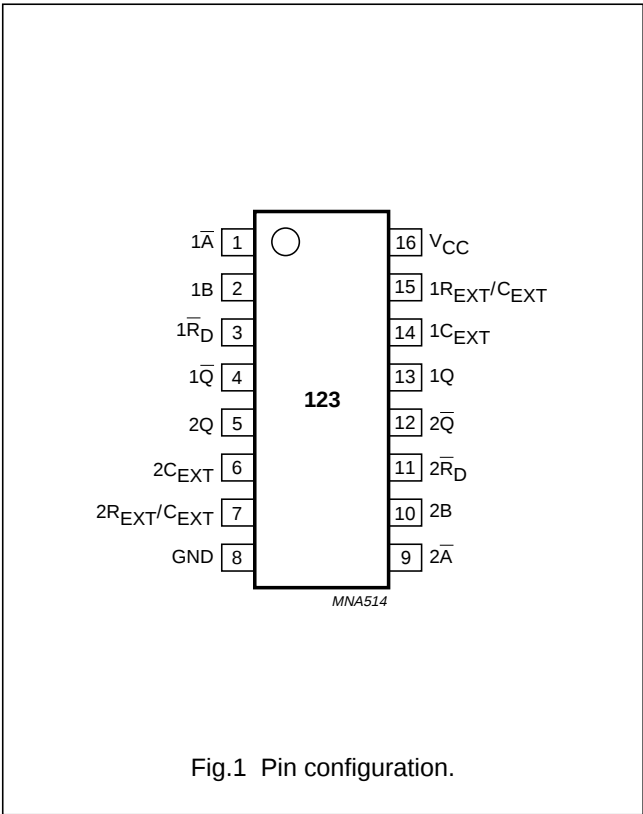
TYPE NUMBER	PACKAGES				
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE
74AHC123AD	-40 to +125 °C	16	SO	plastic	SOT109-1
74AHC123APW		16	TSSOP	plastic	SOT403-1
74AHCT123AD		16	SO	plastic	SOT109-1
74AHCT123APW		16	TSSOP	plastic	SOT403-1

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PINNING

PIN	SYMBOL	DESCRIPTION
1, 9	$1\bar{A}, 2\bar{A}$	trigger inputs (negative-edge triggered)
2, 10	1B, 2B	trigger inputs (positive-edge triggered)
3, 11	$1\bar{R}_D, 2\bar{R}_D$	direct reset LOW and trigger action at positive edge
4, 12	$1\bar{Q}, 2\bar{Q}$	outputs (active LOW)
5, 13	2Q, 1Q	outputs (active HIGH)
6, 14	$2C_{EXT}, 1C_{EXT}$	external capacitor connection
7, 15	$2R_{EXT}/C_{EXT}, 1R_{EXT}/C_{EXT}$	external resistor/capacitor connection
8	GND	ground (0 V)
16	V_{CC}	DC supply voltage



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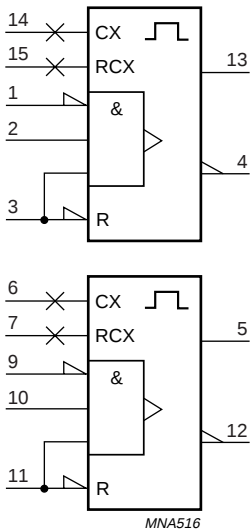


Fig.3 IEC logic symbol.

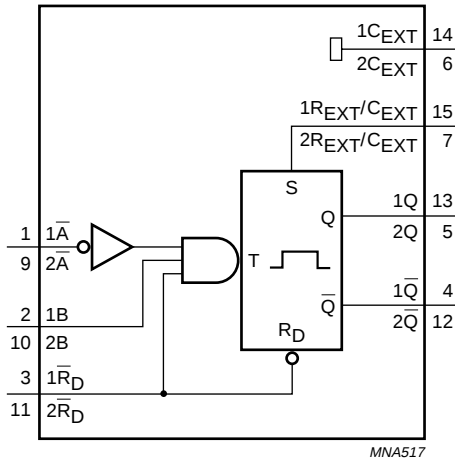
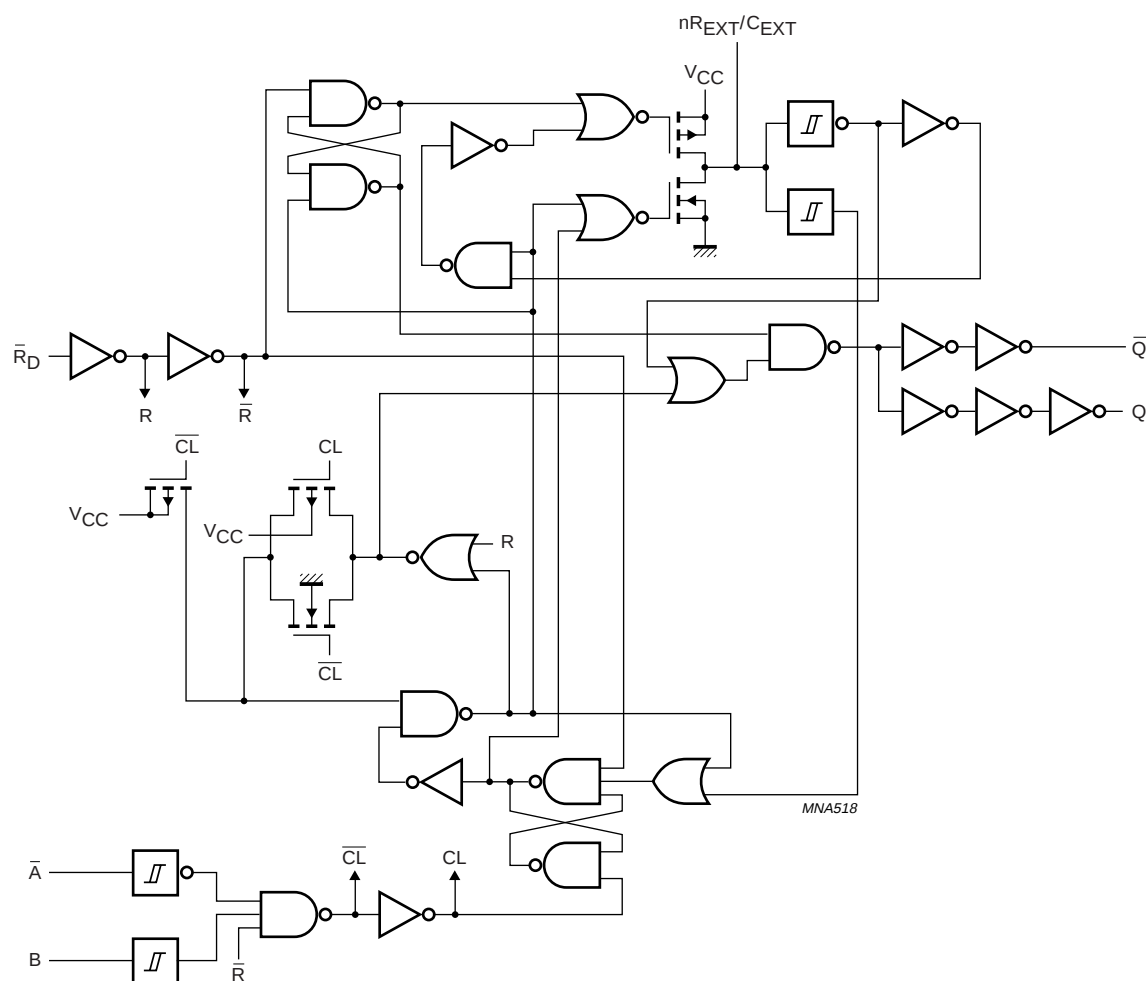


Fig.4 Functional diagram.

Dual retriggerable monostable multivibrator with reset

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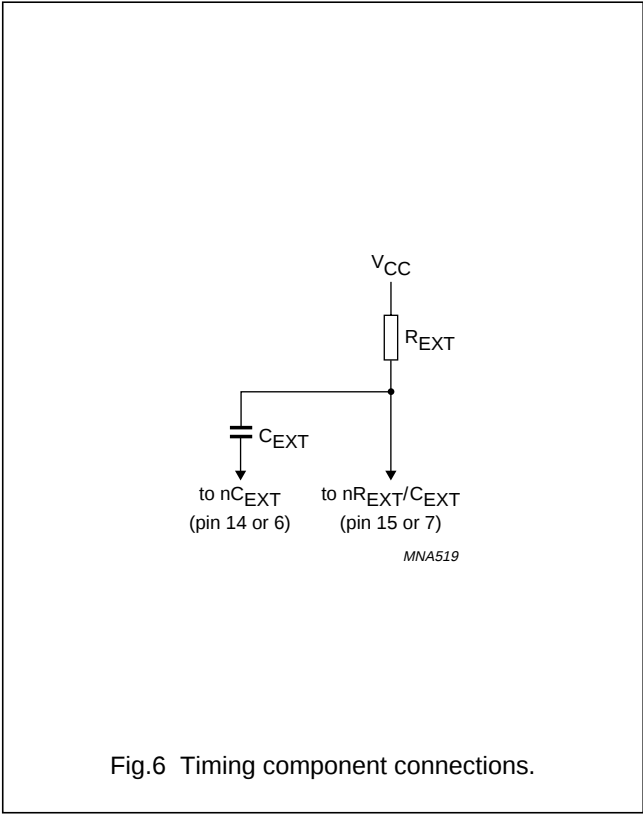


For minimum noise generation, it is recommended to ground pins 6 (2CEXT) and 14 (1CEXT) externally to pin 8 (GND).

Fig.5 Logic diagram (one flip-flop).

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	74AHC			74AHCT			UNIT
			MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
V_{CC}	DC supply voltage		2.0	5.0	5.5	4.5	5.0	5.5	V
V_I	input voltage		0	–	5.5	0	–	5.5	V
V_O	output voltage		0	–	V_{CC}	0	–	V_{CC}	V
T_{amb}	operating ambient temperature	see DC and AC characteristics per device	–40	+25	+85	–40	+25	+85	°C
			–40	+25	+125	–40	+25	+125	°C
t_r, t_f	input rise and fall time ratios	$V_{CC} = 3.3 \pm 0.3 \text{ V}$	–	–	100	–	–	–	ns/V
		$V_{CC} = 5 \pm 0.5 \text{ V}$	–	–	20	–	–	20	ns/V
R_{EXT}	external timing resistor	$V_{CC} = 2 \text{ V}$	5	–	–	5	–	–	k Ω
		$V_{CC} > 3 \text{ V}$	1	–	–	1	–	–	k Ω
C_{EXT}	external timing capacitor		no limits						pF

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	DC supply voltage		-0.5	+7.0	V
V_I	input voltage		-0.5	+7.0	V
I_{IK}	DC input diode current	$V_I < -0.5$ V; note 1	–	-20	mA
I_{OK}	DC output clamping diode current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V; note 1	–	±20	mA
I_O	DC output sink current	-0.5 V $< V_O < V_{CC} + 0.5$ V	–	±25	mA
I_{CC}	DC V_{CC} or GND current		–	±75	mA
T_{stg}	storage temperature		-65	+150	°C
P_D	power dissipation per package	for temperature range: -40 to +125 °C; note 2	–	500	mW

Notes

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. For SO packages: above 70 °C the value of P_D derates linearly with 8 mW/K.
For TSSOP packages: above 60 °C the value of P_D derates linearly with 5.5 mW/K.

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DC CHARACTERISTICS

Family 74AHC

Over recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		T _{amb} (°C)							UNIT
		OTHER	V _{CC} (V)	25			–40 to +85		–40 to +125		
				MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.	
V _{IH}	HIGH-level input voltage		2.0	1.5	–	–	1.5	–	1.5	–	V
			3.0	2.1	–	–	2.1	–	2.1	–	V
			5.5	3.85	–	–	3.85	–	3.85	–	V
V _{IL}	LOW-level input voltage		2.0	–	–	0.5	–	0.5	–	0.5	V
			3.0	–	–	0.9	–	0.9	–	0.9	V
			5.5	–	–	1.65	–	1.65	–	1.65	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL} ; I _O = –50 μA	2.0	1.9	2.0	–	1.9	–	1.9	–	V
			3.0	2.9	3.0	–	2.9	–	2.9	–	V
			4.5	4.4	4.5	–	4.4	–	4.4	–	V
		V _I = V _{IH} or V _{IL} ; I _O = –4.0 mA	3.0	2.58	–	–	2.48	–	2.40	–	V
		V _I = V _{IH} or V _{IL} ; I _O = –8.0 mA	4.5	3.94	–	–	3.8	–	3.70	–	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL} ; I _O = 50 μA	2.0	–	0	0.1	–	0.1	–	0.1	V
			3.0	–	0	0.1	–	0.1	–	0.1	V
			4.5	–	0	0.1	–	0.1	–	0.1	V
		V _I = V _{IH} or V _{IL} ; I _O = 4.0 mA	3.0	–	–	0.36	–	0.44	–	0.55	V
		V _I = V _{IH} or V _{IL} ; I _O = 8.0 mA	4.5	–	–	0.36	–	0.44	–	0.55	V
I _I	input leakage current; R _{EXT} /C _{EXT}	V _I = V _{CC} or GND; note 1	5.5	–	–	±0.25	–	±2.5	–	±10.0	μA
	input leakage current; n $\overline{A}$, nB, n $\overline{R}_D$	V _I = V _{CC} or GND	5.5	–	–	±0.1	–	±1.0	–	±2.0	μA
I _{CC}	quiescent supply current	V _I = V _{CC} or GND; I _O = 0	5.5	–	–	4.0	–	40	–	80	μA
	quiescent supply current active state (per circuit)	V _I = V _{CC} or GND; note 1	3	–	160	250	–	280	–	280	μA
			4.5	–	380	500	–	650	–	650	μA
			5.5	–	560	750	–	975	–	975	μA
C _I	input capacitance		–	–	5	10	–	10	–	10	pF

Note

1. Voltage on pin nR_{EXT}/C_{EXT} = 0.5 × V_{CC} and pin R_{EXT}/C_{EXT} in OFF-state during test.

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Family 74AHCT

Over recommended operating conditions; voltage are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		T _{amb} (°C)							UNIT
		OTHER	V _{CC} (V)	25			–40 to +85		–40 to +125		
				MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.	
V _{IH}	HIGH-level input voltage		4.5 to 5.5	2.0	–	–	2.0	–	2.0	–	V
V _{IL}	LOW-level input voltage		4.5 to 5.5	–	–	0.8	–	0.8	–	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL} ; I _O = –50 μA	4.5	4.4	4.5	–	4.4	–	4.4	–	V
		V _I = V _{IH} or V _{IL} ; I _O = –8.0 mA	4.5	3.94	–	–	3.8	–	3.70	–	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL} ; I _O = 50 μA	4.5	–	0	0.1	–	0.1	–	0.1	V
		V _I = V _{IH} or V _{IL} ; I _O = 8.0 mA	4.5	–	–	0.36	–	0.44	–	0.55	V
I _I	input leakage current; R _{EXT} /C _{EXT}	V _I = V _{CC} or GND; note 1	5.5	–	–	±0.25	–	±2.5	–	±10.0	μA
	input leakage current; nA, nB, nR _D	V _I = V _{CC} or GND	5.5	–	–	±0.1	–	±1.0	–	±2.0	μA
I _{CC}	quiescent supply current	V _I = V _{CC} or GND; I _O = 0	5.5	–	–	4.0	–	40	–	80	μA
	quiescent supply current active state (per circuit)	V _I = V _{CC} or GND; note 1	4.5	–	380	500	–	650	–	650	μA
			5.5	–	560	750	–	975	–	975	μA
C _I	input capacitance		–	–	3	10	–	10	–	10	pF

Note

1. Voltage on pin nR_{EXT}/C_{EXT} = 0.5 × V_{CC} and pin R_{EXT}/C_{EXT} in OFF-state during test.

Dual retriggerable monostable multivibrator with reset

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AC CHARACTERISTICS

Type 74AHC123A

GND = 0 V; $t_r = t_f \leq 3.0$ ns.

SYMBOL	PARAMETER	TEST CONDITIONS		T _{amb} (°C)								UNIT
		WAVEFORMS	C _L	25			–40 to +85		–40 to +125			
				MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.		
V _{CC} = 3.0 to 3.6 V; note 1												
t _{PHL} /t _{PLH}	propagation delay; n $\overline{A}$, nB to nQ, n $\overline{Q}$	C _{EXT} = 0 pF; R _{EXT} = 5 k Ω ; see Figs 7 and 11	15 pF	–	7.4	20.6	1.0	24.0	1.0	26.0	ns	
	propagation delay; n $\overline{R}_D$ to nQ, n $\overline{Q}$	C _{EXT} = 0 pF; R _{EXT} = 5 k Ω ; see Figs 7 and 11		–	8.2	22.4	1.0	26.0	1.0	26.0	ns	
	propagation delay; n $\overline{R}_D$ to nQ, n $\overline{Q}$ (reset)	C _{EXT} = 0 pF; R _{EXT} = 5 k Ω ; see Figs 7 and 11		–	6.4	15.8	1.0	18.5	1.0	20.0	ns	
	propagation delay; n $\overline{A}$, nB to nQ , n $\overline{Q}$	C _{EXT} = 0 pF; R _{EXT} = 5 k Ω ; see Figs 7 and 11	50 pF	–	10.5	24.1	1.0	27.5	1.0	30.0	ns	
	propagation delay; n $\overline{R}_D$ to nQ, n $\overline{Q}$	C _{EXT} = 0 pF; R _{EXT} = 5 k Ω ; see Figs 7 and 11		–	11.7	25.9	1.0	29.5	1.0	32.0	ns	
	propagation delay; n $\overline{R}_D$ to nQ, n $\overline{Q}$ (reset)	C _{EXT} = 0 pF; R _{EXT} = 5 k Ω ; see Figs 7 and 11		–	9.2	19.3	1.0	22.0	1.0	24.5	ns	
t _w	trigger pulse width; n $\overline{A}$ = LOW	see Fig 8		5.0	–	–	5.0	–	5.0	–	ns	
	trigger pulse width; nB = HIGH	see Fig 8		5.0	–	–	5.0	–	5.0	–	ns	
	reset pulse width; n $\overline{R}_D$ = LOW	see Fig 9		5.0	–	–	5.0	–	5.0	–	ns	
	output pulse width; nQ = HIGH; n $\overline{Q}$ = LOW	C _{EXT} = 28 pF; R _{EXT} = 2 k Ω ; note 3; see Figs 8, 9 and 10		–	115	240	–	300	–	300	ns	
		C _{EXT} = 0.01 μ F; R _{EXT} = 10 k Ω ; note 3; see Figs 8, 9 and 10		90	100	110	90	110	85	115	μ s	
		C _{EXT} = 0.1 μ F; R _{EXT} = 10 k Ω ; note 3; see Figs 8, 9 and 10		0.9	1	1.1	0.9	1.1	0.85	1.15	ms	

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SYMBOL	PARAMETER	TEST CONDITIONS		T _{amb} (°C)							UNIT
		WAVEFORMS	C _L	25			–40 to +85		–40 to +125		
				MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.	
V _{CC} = 3.0 to 3.6 V; note 1											
t _{rt}	retrigger time; nA to nB	C _{EXT} = 100 pF; R _{EXT} = 1 kΩ; see Figs 8, 9 and 10	50 pF	–	60	–	–	–	–	–	ns
		C _{EXT} = 0.01 μF; R _{EXT} = 1 kΩ; see Figs 8, 9 and 10		–	1.5	–	–	–	–	–	μs
V _{CC} = 4.5 to 5.5 V; note 2											
t _{PHL} /t _{PLH}	propagation delay; nA, nB to nQ, nQ̄	C _{EXT} = 0 pF; R _{EXT} = 5 kΩ; see Figs 7 and 11	15 pF	–	5.1	12	1.0	14.0	1.0	15.5	ns
	propagation delay; nR _D to nQ, nQ̄	C _{EXT} = 0 pF; R _{EXT} = 5 kΩ; see Figs 7 and 11		–	5.6	12.9	1.0	15.0	1.0	16.5	ns
	propagation delay; nR _D to nQ, nQ̄ (reset)	C _{EXT} = 0 pF; R _{EXT} = 5 kΩ; see Figs 7 and 11		–	4.4	9.4	1.0	11.0	1.0	12.0	ns
	propagation delay; nA, nB to nQ, nQ̄	C _{EXT} = 0 pF; R _{EXT} = 5 kΩ; see Figs 7 and 11	50 pF	–	7.3	14	1.0	16.0	1.0	17.5	ns
	propagation delay; nR _D to nQ, nQ̄	C _{EXT} = 0 pF; R _{EXT} = 5 kΩ; see Figs 7 and 11		–	8.1	14.9	1.0	17.0	1.0	19.0	ns
	propagation delay; nR _D to nQ, nQ̄ (reset)	C _{EXT} = 0 pF; R _{EXT} = 5 kΩ; see Figs 7 and 11		–	6.3	11.4	1.0	13.0	1.0	14.5	ns

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SYMBOL	PARAMETER	TEST CONDITIONS		T _{amb} (°C)								UNIT
		WAVEFORMS	C _L	25			–40 to +85		–40 to +125			
				MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.		
V _{CC} = 4.5 to 5.5 V; note 2												
t _w	trigger pulse width; nA = LOW	see Fig 8	50 pF	5.0	–	–	5.0	–	5.0	–	ns	
	trigger pulse width; nB = HIGH	see Fig 8		5.0	–	–	5.0	–	5.0	–	ns	
	reset pulse width; nR _D = LOW	see Fig 9		5.0	–	–	5.0	–	5.0	–	ns	
	output pulse width; nQ = HIGH; nQ̄ = LOW	C _{EXT} = 28 pF; R _{EXT} = 2 kΩ; note 3; see Figs 8, 9 and 10		–	100	200	–	240	–	240	ns	
		C _{EXT} = 0.01 μF; R _{EXT} = 10 kΩ; note 3; see Figs 8, 9 and 10		90	100	110	90	110	85	115	μs	
		C _{EXT} = 0.1 μF; R _{EXT} = 10 kΩ; note 3; see Figs 8, 9 and 10		0.9	1	1.1	0.9	1.1	0.85	1.15	ms	
	t _{rt}	retrigger time; nĀ to nB		C _{EXT} = 100 pF; R _{EXT} = 1 kΩ; see Figs 8, 9 and 10	–	39	–	–	–	–	–	ns
C _{EXT} = 0.01 μF; R _{EXT} = 1 kΩ; see Figs 8, 9 and 10			–	1.2	–	–	–	–	–	μs		

Notes

- Typical values are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.
- Typical values are measured at V_{CC} = 5.0 V and T_{amb} = 25 °C.
- For C_{EXT} ≥ 10 nF the typical value of the pulse width t_w (μs) = R_{EXT} (kΩ) × C_{EXT} (nF).

Dual retriggerable monostable multivibrator with reset

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Type 74AHCT123A

GND = 0 V; $t_r = t_f \leq 3.0$ ns.

SYMBOL	PARAMETER	TEST CONDITIONS		T _{amb} (°C)							UNIT
		WAVEFORMS	C _L	25			–40 to +85		–40 to +125		
				MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.	
V _{CC} = 4.5 to 5.5 V; note 1											
t _{PHL} /t _{PLH}	propagation delay; nA, nB to nQ, nQ̄	C _{EXT} = 0 pF; R _{EXT} = 5 kΩ; see Figs 7 and 11	15 pF	–	5.0	12	1.0	14	1.0	15.5	ns
	propagation delay; nR _D to nQ, nQ̄	C _{EXT} = 0 pF; R _{EXT} = 5 kΩ; see Figs 7 and 11		–	5.2	12.9	1.0	15.0	1.0	16.5	ns
	propagation delay; nR _D to nQ, nQ̄ (reset)	C _{EXT} = 0 pF; R _{EXT} = 5 kΩ; see Figs 7 and 11		–	4.7	9.4	1.0	11	1.0	12.0	ns
	propagation delay; nA, nB to nQ, nQ̄	C _{EXT} = 0 pF; R _{EXT} = 5 kΩ; see Figs 7 and 11	50 pF	–	7.1	14	1.0	16	1.0	17.5	ns
	propagation delay; nR _D to nQ, nQ̄	C _{EXT} = 0 pF; R _{EXT} = 5 kΩ; see Figs 7 and 11		–	7.5	14.9	1.0	17.0	1.0	18.5	ns
	propagation delay; nR _D to nQ, nQ̄ (reset)	C _{EXT} = 0 pF; R _{EXT} = 5 kΩ; see Figs 7 and 11		–	6.7	11.4	1.0	13	1.0	14.5	ns
t _w	trigger pulse width; nA = LOW	see Fig 8	50 pF	5.0	–	–	5.0	–	5.0	–	ns
	trigger pulse width; nB = HIGH	see Fig 8		5.0	–	–	5.0	–	5.0	–	ns
	reset pulse width; nR _D = LOW	see Fig 9		5.0	–	–	5.0	–	5.0	–	ns
	output pulse width; nQ = HIGH; nQ̄ = LOW	C _{EXT} = 28 pF; R _{EXT} = 2 kΩ; note 2; see Figs 8, 9 and 10		–	100	200	–	240	–	240	ns
		C _{EXT} = 0.01 μF; R _{EXT} = 10 kΩ; note 2; see Figs 8, 9 and 10		90	100	110	90	110	85	115	μs
		C _{EXT} = 0.1 μF; R _{EXT} = 10 kΩ; note 2; see Figs 8, 9 and 10		0.9	1	1.1	0.9	1.1	0.85	1.15	ms

Dual retriggerable monostable multivibrator with reset

74AHC123A;
74AHCT123A

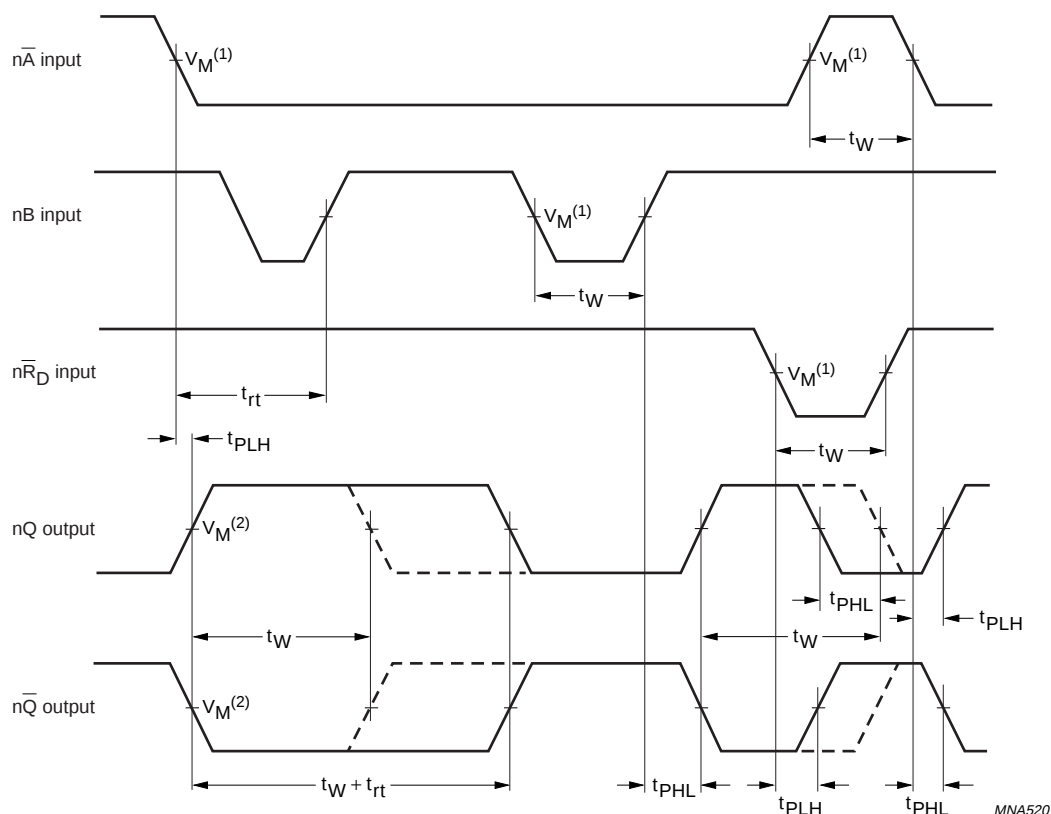
SYMBOL	PARAMETER	TEST CONDITIONS		T _{amb} (°C)								UNIT
		WAVEFORMS	C _L	25			−40 to +85		−40 to +125			
				MIN.	TYP.	MAX.	MIN.	MAX.	MIN.	MAX.		
V _{CC} = 4.5 to 5.5 V; note 1												
t _{rt}	retrigger time; nA to nB	C _{EXT} = 100 pF; R _{EXT} = 1 kΩ; see Figs 8, 9 and 10	50 pF	—	60	—	—	—	—	—	—	ns
		C _{EXT} = 0.01 μF; R _{EXT} = 1 kΩ; see Figs 8, 9 and 10		—	1.5	—	—	—	—	—	μs	

Notes

- Typical values are measured at V_{CC} = 5.0 V and T_{amb} = 25 °C.
- For C_{EXT} ≥ 10 nF the typical value of the pulse width t_W (μs) = R_{EXT} (kΩ) × C_{EXT} (nF).

74AHC123A;
74AHCT123A

AC WAVEFORMS



FAMILY	V _I INPUT REQUIREMENTS	V _M ⁽¹⁾ INPUT	V _M ⁽²⁾ OUTPUT
AHC	GND to V _{CC}	50% V _{CC}	50% V _{CC}
AHCT	GND to 3.0 V	1.5 V	50% V _{CC}

Fig.7 Input ($n\bar{A}$, nB , $n\bar{R}_D$) to output (nQ , $n\bar{Q}$) propagation delays, the input and output pulse widths and the input retrigger time.

Dual retriggerable monostable multivibrator with reset

74AHC123A;
74AHCT123A

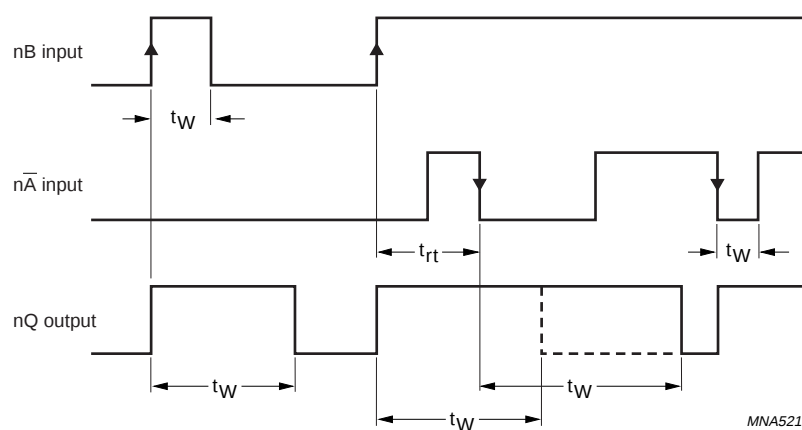


Fig.8 Output pulse control using retrigger pulse; $n\bar{R}_D = \text{HIGH}$.

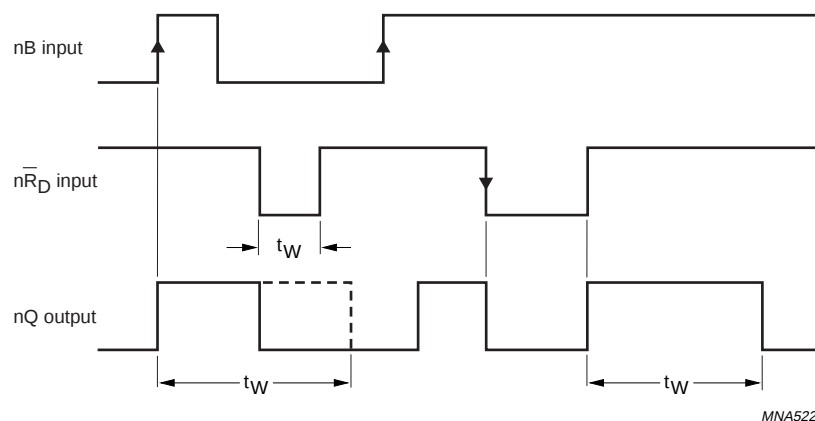
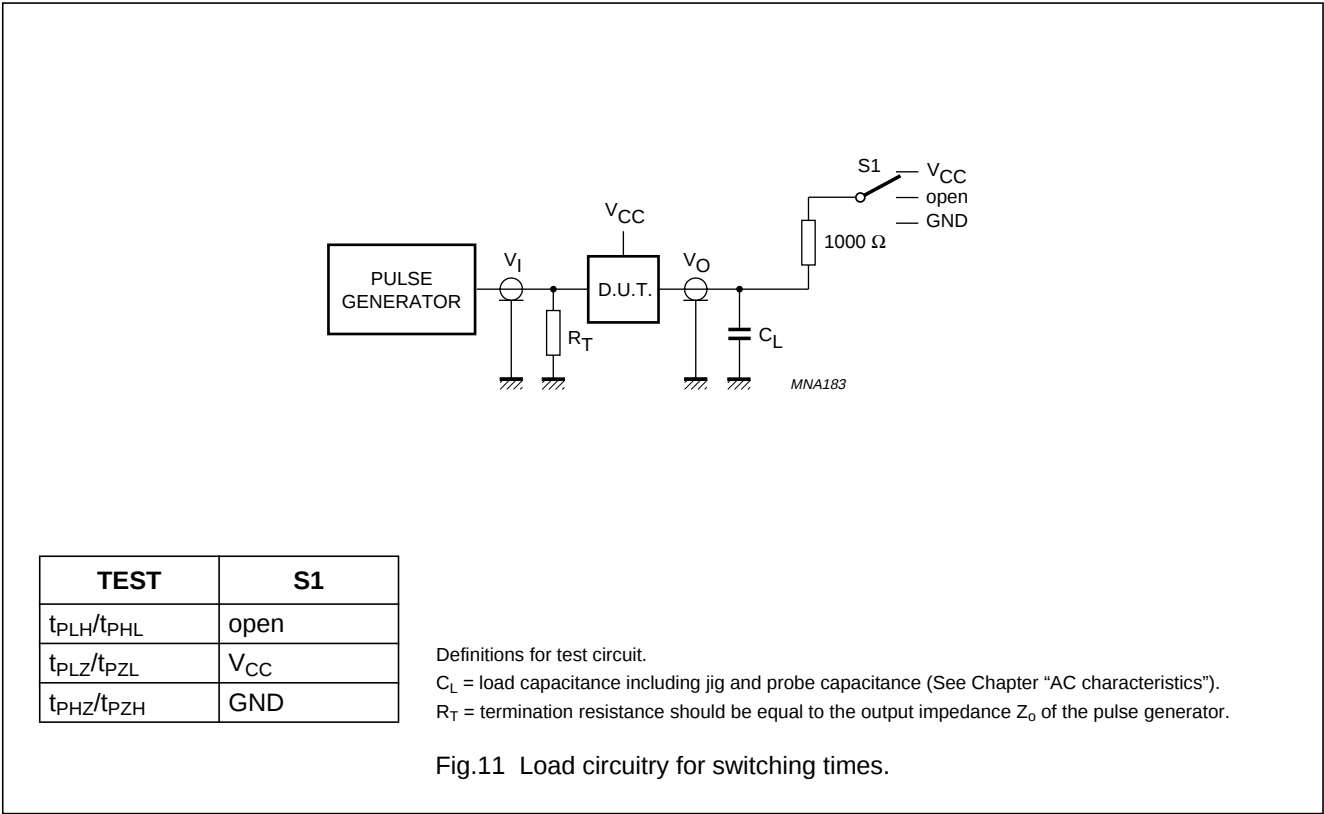
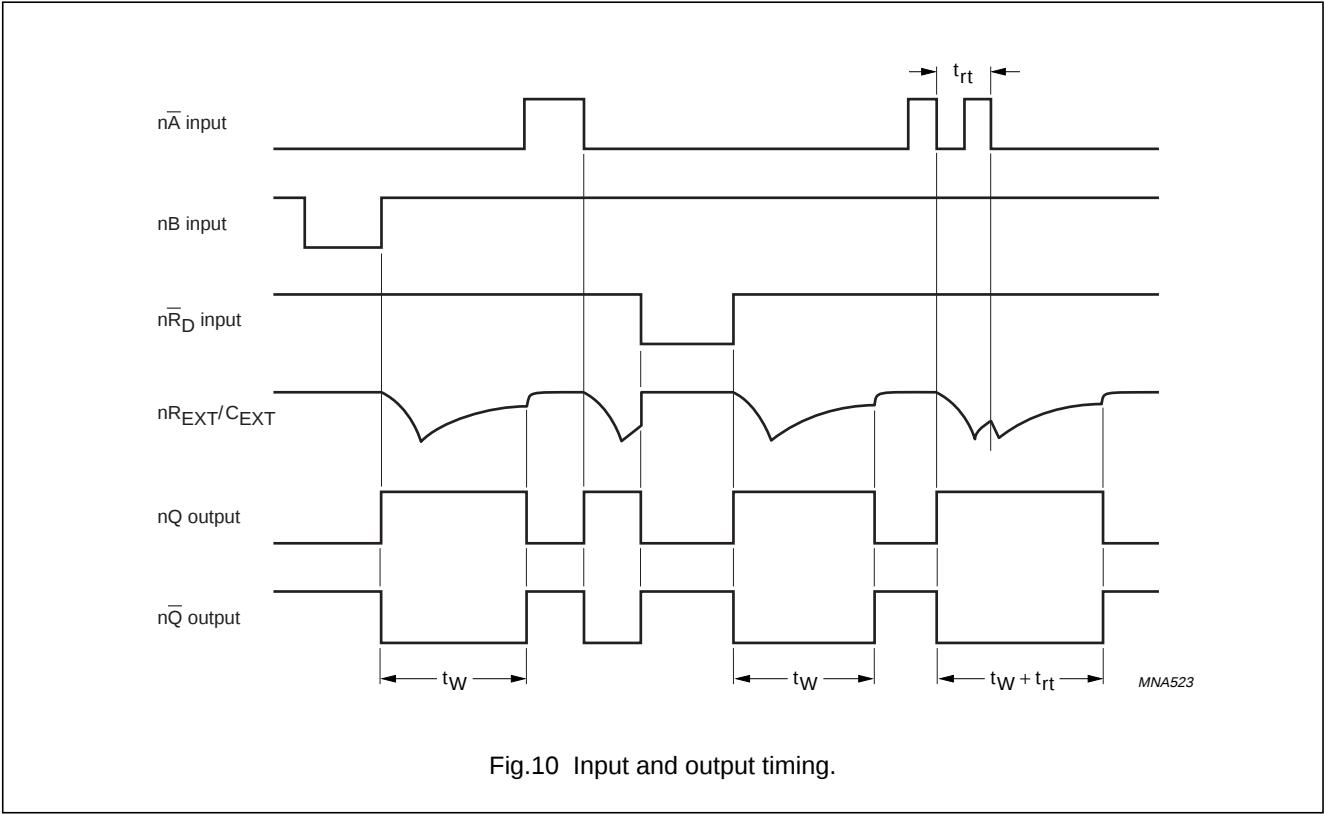


Fig.9 Output pulse control using reset input $n\bar{R}_D$; $n\bar{A} = \text{LOW}$.

Dual retriggerable monostable multivibrator
with reset

74AHC123A;
74AHCT123A



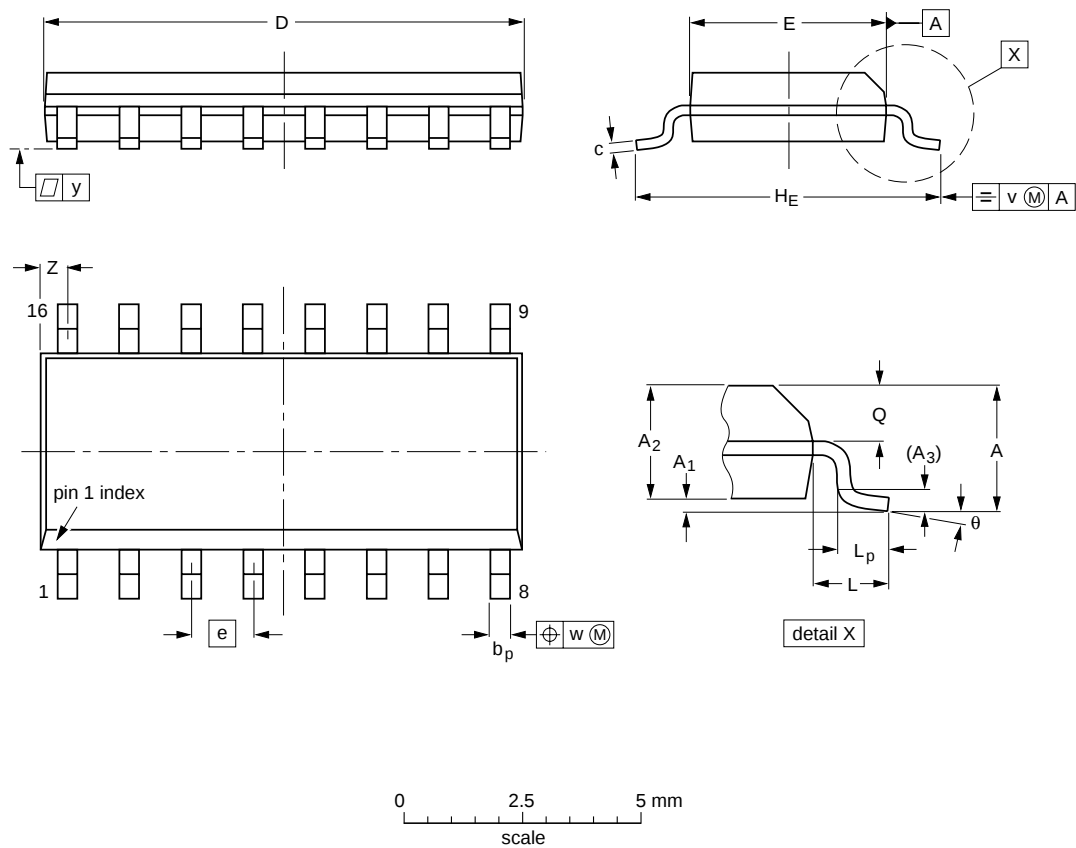
Dual retriggerable monostable multivibrator
with reset

74AHC123A;
74AHCT123A

PACKAGE OUTLINES

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

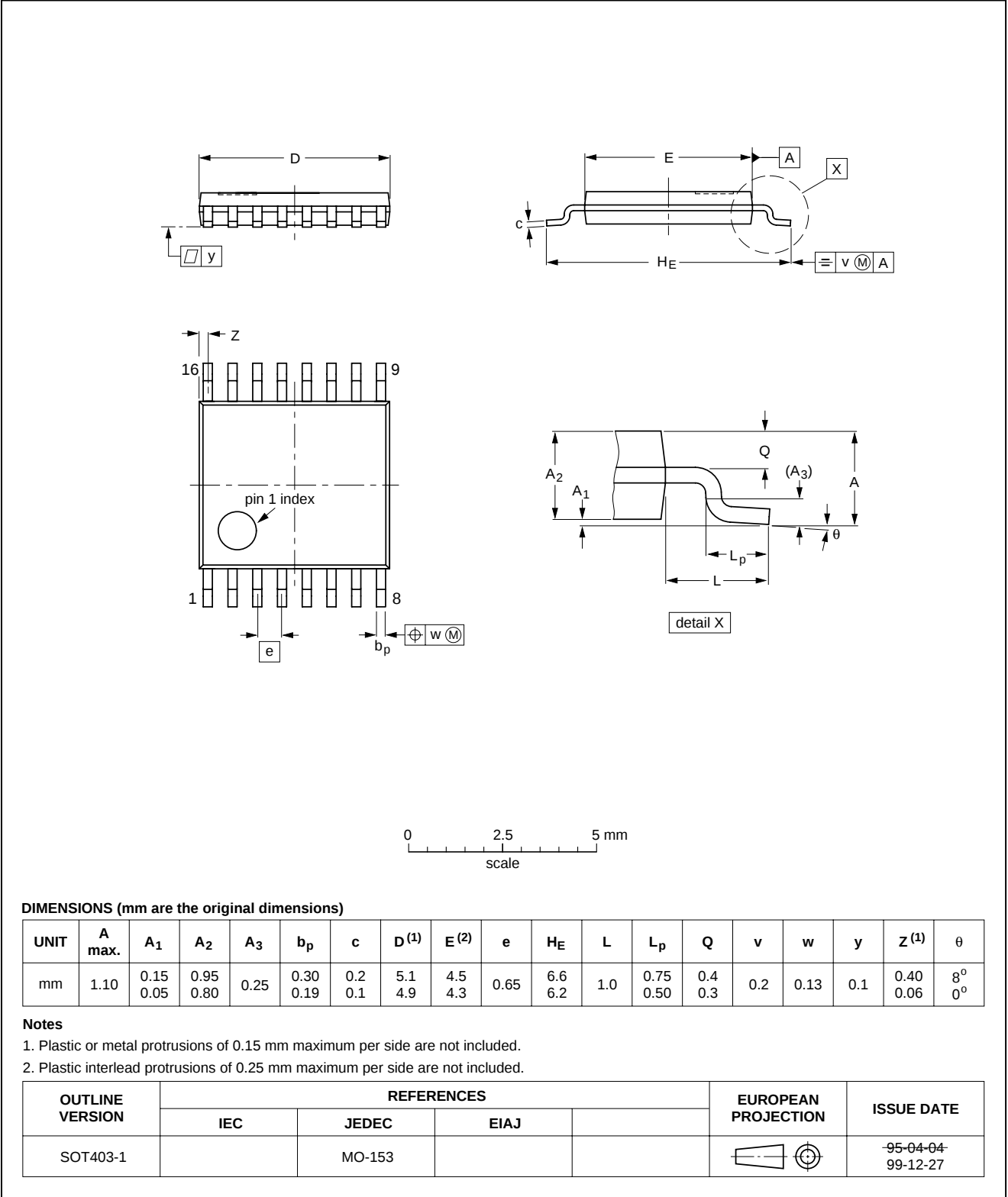
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT109-1	076E07	MS-012				97-05-22 99-12-27

Dual retriggerable monostable multivibrator
with reset

74AHC123A;
74AHCT123A

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1



Dual retriggerable monostable multivibrator with reset

74AHC123A;
74AHCT123A

SOLDERING

Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering is not always suitable for surface mount ICs, or for printed-circuit boards with high population densities. In these situations reflow soldering is often used.

Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, infrared/convection heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferably be kept below 230 °C.

Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
 - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
 - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

Dual retriggerable monostable multivibrator with reset

74AHC123A;
74AHCT123A

Suitability of surface mount IC packages for wave and reflow soldering methods

PACKAGE	SOLDERING METHOD	
	WAVE	REFLOW ⁽¹⁾
BGA, LFBGA, SQFP, TFBGA	not suitable	suitable
HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, SMS	not suitable ⁽²⁾	suitable
PLCC ⁽³⁾ , SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended ⁽³⁾⁽⁴⁾	suitable
SSOP, TSSOP, VSO	not recommended ⁽⁵⁾	suitable

Notes

1. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the *"Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods"*.
2. These packages are not suitable for wave soldering as a solder joint between the printed-circuit board and heatsink (at bottom version) can not be achieved, and as solder may stick to the heatsink (on top version).
3. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
4. Wave soldering is only suitable for LQFP, TQFP and QFP packages with a pitch (e) equal to or larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
5. Wave soldering is only suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

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